Dual D-Type Flip-Flop with Set and Reset

The MC74VHCT74A is an advanced high speed CMOS D-type flip-flop fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The signal level applied to the D input is transferred to Q output during the positive going transition of the Clock pulse.

Reset (\overline{RD}) and Set (\overline{SD}) are independent of the Clock (CP) and are accomplished by setting the appropriate input Low.

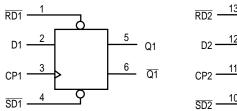
The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to 7V, allowing the interface of 5V systems to 3V systems.

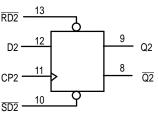
The VHCT inputs are compatible with TTL levels. This device can be used as a level converter for interfacing 3.3V to 5.0V, because it has full 5V CMOS level output swings.

The VHCT74A input structures provide protection when voltages between 0V and 5.5V are applied, regardless of the supply voltage. The output structures also provide protection when VCC=0V. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

- High Speed: $f_{max} = 60MHz$ (Typ) at $V_{CC} = 5V$
- Low Power Dissipation: $I_{CC} = 2\mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 4.5V to 5.5V Operating Range
- Low Noise: Volp = 0.8V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 2000V; Machine Model > 200V
- Chip Complexity: 128 FETs or 32 Equivalent Gates

LOGIC DIAGRAM





FUNCTION TABLE

	Inp	Out	puts		
SD	RD	CP	D	Q	Q
L	Н	Х	Χ	Н	Г
Н	L	Χ	Χ	L	Н
L	L	Χ	Χ	H*	H*
Н	Н		Н	Н	L
Н	Н		L	L	Н
Н	Н	L	Χ	No Cl	nange
Н	Н	Н	Χ	No Ch	nange
Н	Н	\sim	Χ	No Cl	nange

^{*} Both outputs will remain high as long as Set and Reset are low, but the output states are unpredictable if Set and Reset go high simultaneously.

MC74VHCT74A



D SUFFIX 14–LEAD SOIC PACKAGE CASE 751A–03



DT SUFFIX 14-LEAD TSSOP PACKAGE CASE 948G-01

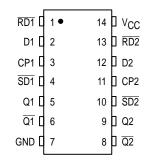


M SUFFIX 14-LEAD SOIC EIAJ PACKAGE CASE 965-01

ORDERING INFORMATION

MC74VHCTXXAD SOIC
MC74VHCTXXADT TSSOP
MC74VHCTXXAM SOIC EIAJ

PIN ASSIGNMENT





MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage	- 0.5 to + 7.0	V
V _{in}	DC Input Voltage	- 0.5 to + 7.0	V
V _{out}	DC Output Voltage $V_{CC} = 0$ High or Low State	- 0.5 to + 7.0 - 0.5 to V _{CC} + 0.5	V
lικ	Input Diode Current	- 20	mA
lok	Output Diode Current (VOUT < GND; VOUT > VCC)	± 20	mA
l _{out}	DC Output Current, per Pin	± 25	mA
ICC	DC Supply Current, V _{CC} and GND Pins	± 50	mA
PD	Power Dissipation in Still Air, SOIC Packages† TSSOP Package†	500 450	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C

Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

†Derating — SOIC Packages: - 7 mW/°C from 65° to 125°C TSSOP Package: - 6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
VCC	DC Supply Voltage	4.5	5.5	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage $V_{CC} = 0$ High or Low State		5.5 VCC	V
TA	Operating Temperature	- 40	+ 85	°C
t _r , t _f	Input Rise and Fall Time V _{CC} =5.0V ±0.5V	0	20	ns/V

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} . tied to an appropriate logic voltage

Unused inputs must always be level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

			ν _{cc}		T _A = 25°C	;	T _A = -4	0 to 85°C	
Symbol	Parameter	Test Conditions	👸	Min	Тур	Max	Min	Max	Unit
VIH	Minimum High–Level Input Voltage		4.5 to 5.5	2.0			2.0		V
VIL	Maximum Low–Level Input Voltage		4.5 to 5.5			0.8		0.8	V
VOH	Minimum High-Level	I _{OH} = - 50μA	4.5	4.4	4.5		4.4		V
Output Voltage V _{in} = V _{IH} or V _{IL}		I _{OH} = -8mA	4.5	3.94			3.80		1
VOL	Maximum Low–Level Output Voltage	I _{OL} = 50μA	4.5		0.0	0.1		0.1	V
	V _{in} = V _{IH} or V _{IL}	I _{OL} = 8mA	4.5			0.36		0.44	1
lin	Maximum Input Leakage Current	V _{in} = 5.5 V or GND	0 to 5.5			± 0.1		± 1.0	μА
lcc	Maximum Quiescent Supply Current	V _{in} = V _{CC} or GND	5.5			2.0		20.0	μА
ICCT	Quiescent Supply Current	Per Input: V _{IN} = 3.4V Other Input: V _{CC} or GND	5.5			1.35		1.50	mA
lopd	Output Leakage Current	V _{OUT} = 5.5V	0			0.5		5.0	μА

AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0$ ns)

				T _A = 25°C		T _A = - 40 to 85°C			
Symbol	Parameter	Test Condi	tions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, CP to Q or $\overline{\mathbf{Q}}$	$V_{CC} = 5.0 \pm 0.5 V$	$C_L = 15pF$ $C_L = 50pF$		5.8 6.3	7.8 8.8	1.0 1.0	9.0 10.0	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, SD or RD to Q or Q	$V_{CC} = 5.0 \pm 0.5 V$	C _L = 15pF C _L = 50pF		7.6 8.1	10.4 11.4	1.0 1.0	12.0 13.0	ns
fmax	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 5.0 \pm 0.5 V$	C _L = 15pF C _L = 50pF	100 80	160 140		80 65		MHz
C _{in}	Maximum Input Capacitance				4	10		10	pF

		Typical @ 25°C, V _{CC} = 5.0V	
C_{PD}	Power Dissipation Capacitance (Note NO TAG)	24	pF

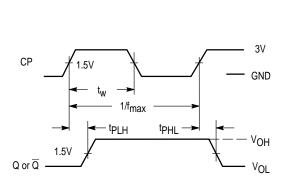
^{1.} CpD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}/2$ (per flip–flop). CpD is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

TIMING REQUIREMENTS (Input $t_f = t_f = 3.0 \text{ns}$)

			Guaranteed Limit		
Symbol	Parameter	v _{CC}	T _A = 25°C	T _A = − 40 to 85°C	Unit
t _W	Minimum Pulse Width, CP	5.0 ± 0.5	5.0	5.0	ns
t _W	Minimum Pulse Width, RD or SD	5.0 ± 0.5	5.0	5.0	ns
t _{su}	Minimum Setup Time, D to CP	5.0 ± 0.5	5.0	5.0	ns
th	Minimum Hold Time, D to CP	5.0 ± 0.5	0.0	0.0	ns
t _{rec}	Minimum Recovery Time, SD or RD to CP	5.0 ± 0.5	3.5	3.5	ns

3

SWITCHING WAVEFORMS



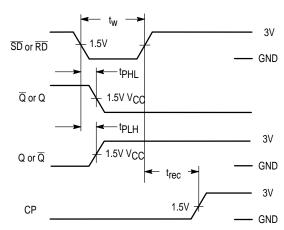


Figure 1.

Figure 2.

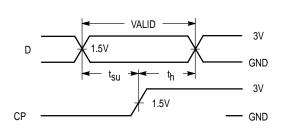
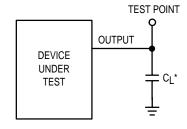


Figure 3.



* Includes all probe and jig capacitance

Figure 4.

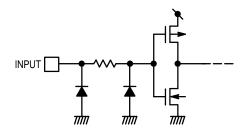
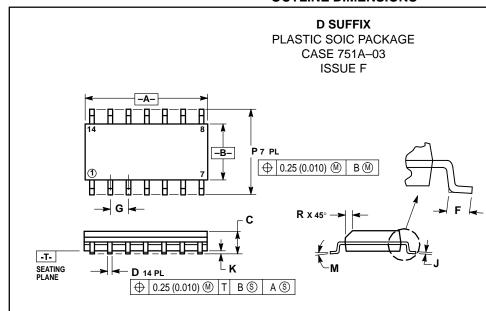


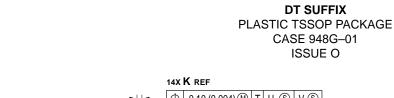
Figure 5. Input Equivalent Circuit

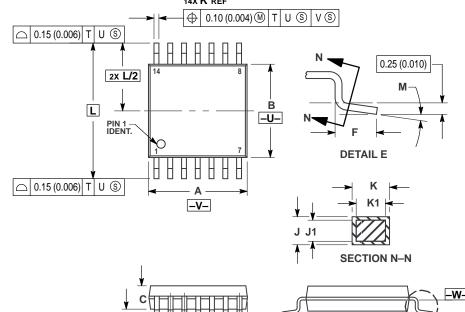
OUTLINE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- THE DIMENSION AND TOLERANCING PEN Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	8.55	8.75	0.337	0.344	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	1.27 BSC		BSC	
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
М	0°	7°	0°	7°	
Р	5.80	6.20	0.228	0.244	
R	0.25	0.50	0.010	0.019	





DETAIL E

5

0.10 (0.004) -T- SEATING PLANE

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- T14:3M, 1992.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH,
 PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- OR GATE BURKS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED
 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20	_	0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
М	N٥	a o	٥°	80	

OUTLINE DIMENSIONS

M SUFFIX PLASTIC SOIC EIAJ PACKAGE CASE 965-01 **ISSUE O** Q_1 Ε ΗE **DETAIL P** VIEW P 0.13 (0.005) M 0.10 (0.004)

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	-	2.05	-	0.081
Α ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
ΗE	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
LF	1.10	1.50	0.043	0.059
М	0 °	10 °	0°	10°
Q_1	0.70	0.90	0.028	0.035
Z		1.42		0.056

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